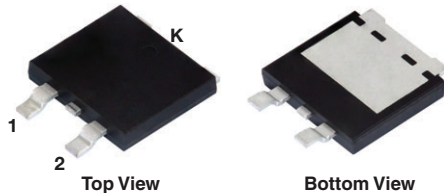


# Dual TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

 Ultra Low  $V_F = 0.55\text{ V}$  at  $I_F = 5\text{ A}$ 

## eSMP<sup>®</sup> Series SMPD (TO-263AC)



### LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	120 V
$I_{FSM}$	120 A
$V_F$ at $I_F = 10\text{ A}$ ( $T_A = 125\text{ °C}$ )	0.65 V
$T_J$ max.	175 °C
Package	SMPD (TO-263AC)
Circuit configuration	Common cathode

### FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak M3 of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

### MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** as marked

### MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V20DM120C	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	120	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$	per device	20
		per diode	10
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	120	A
Voltage rate of change (rated $V_R$ )	$dV/dt$	10 000	V/ $\mu$ s
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +175	°C



<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	$I_F = 5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.65	-	V
	$I_F = 10\text{ A}$			0.85	0.93	
	$I_F = 5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.55	-	
	$I_F = 10\text{ A}$			0.65	0.73	
Reverse current at rated $V_R$ per diode	$V_R = 90\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	23	-	$\mu\text{A}$
		$T_A = 125\text{ }^\circ\text{C}$		1.6	-	mA
	$V_R = 120\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	600	$\mu\text{A}$
		$T_A = 125\text{ }^\circ\text{C}$		3	20	mA

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ 

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER		SYMBOL	V20DM120C	UNIT
Typical thermal resistance	per diode	$R_{\theta JC}$	2.8	$^\circ\text{C/W}$
	per device		1.5	
	per device	$R_{\theta JA}^{(1)(2)}$	48	

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

(2) Free air, without heatsink

<b>ORDERING INFORMATION</b> (Example)					
PACKAGE	PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SMPD (TO-263AC)	V20DM120C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
SMPD (TO-263AC)	V20DM120CHM3/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

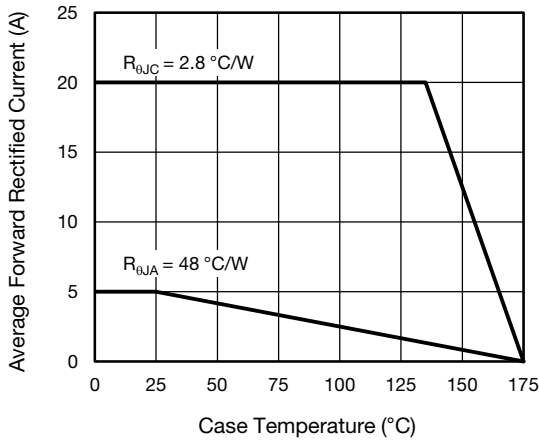


Fig. 1 - Forward Current Derating Curve

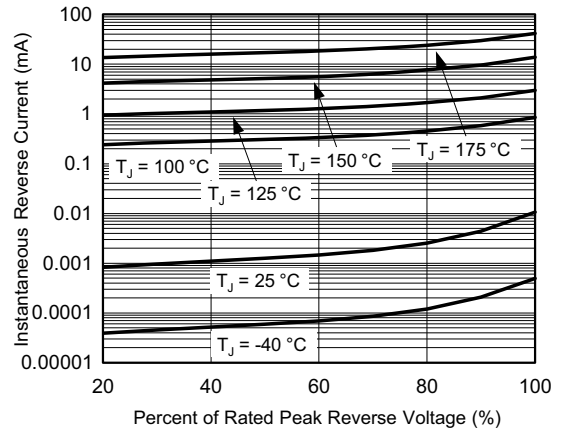


Fig. 4 - Typical Reverse Characteristics Per Diode

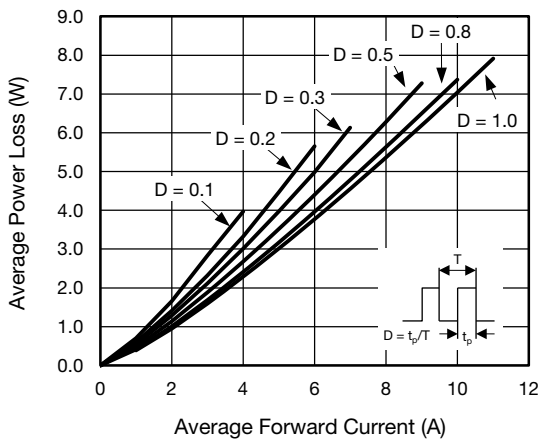


Fig. 2 - Forward Power Loss Characteristics Per Diode

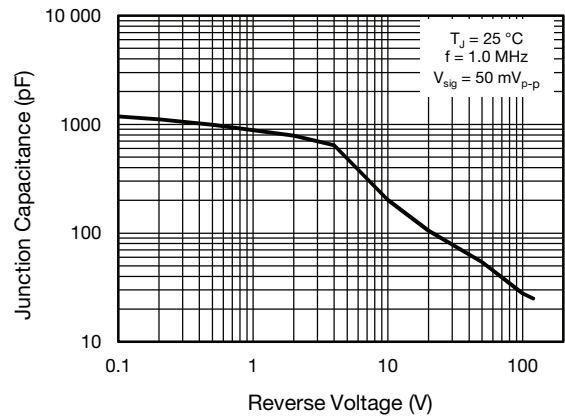


Fig. 5 - Typical Junction Capacitance Per Diode

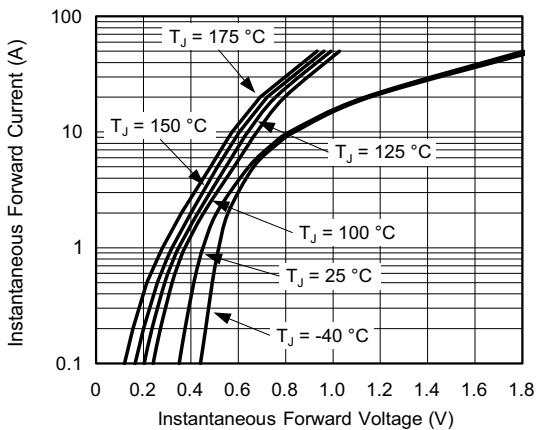


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

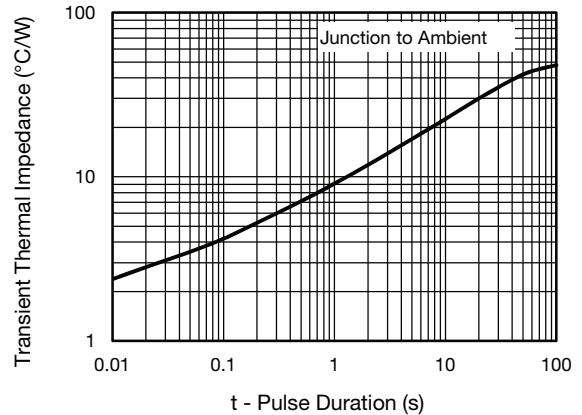


Fig. 6 - Typical Transient Thermal Impedance Per Device

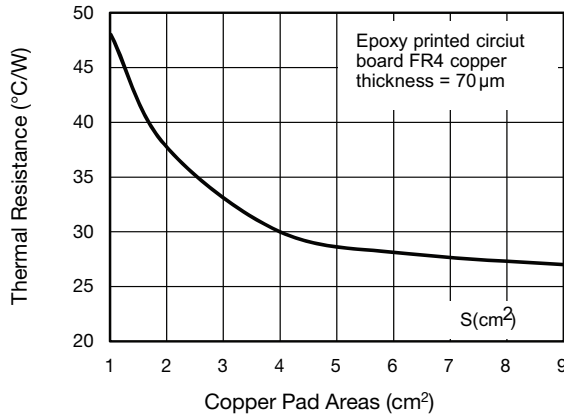
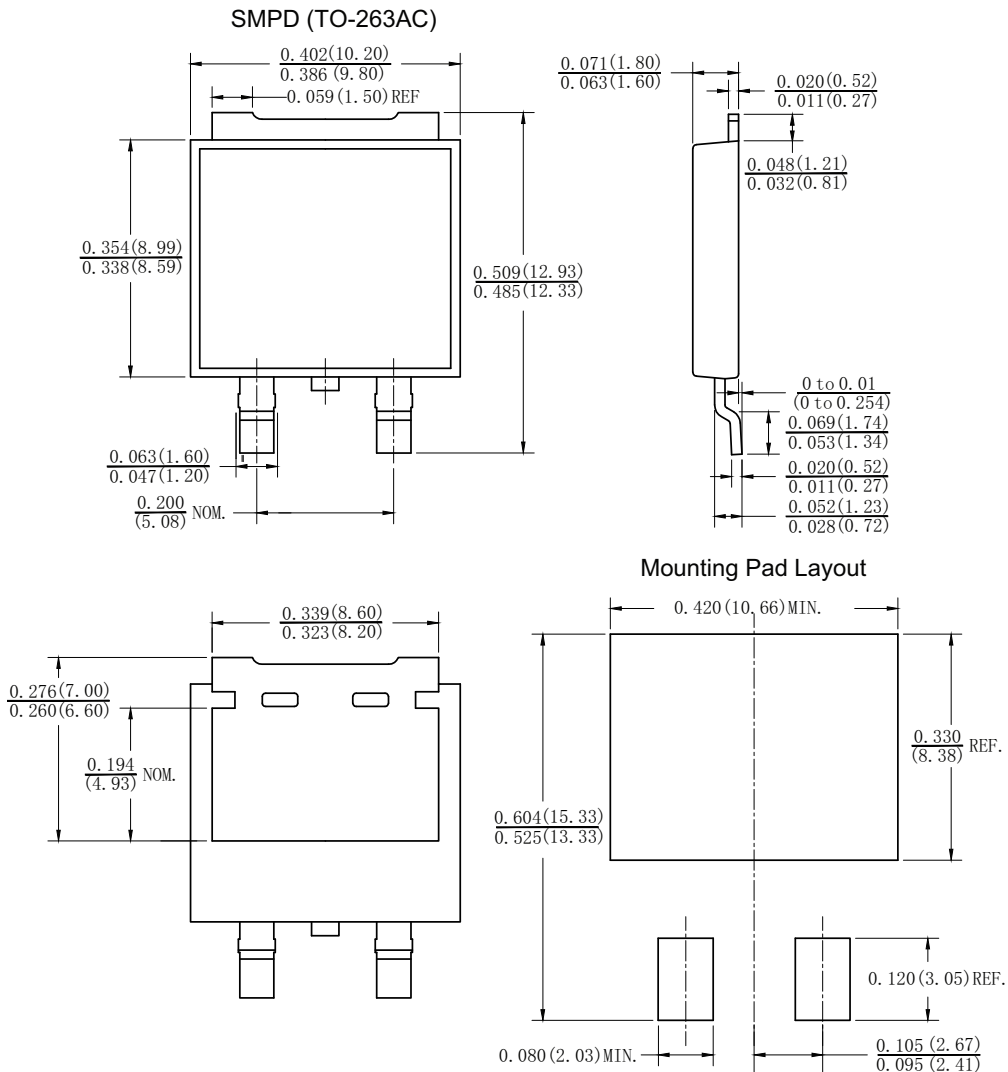


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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